



FOR IMMEDIATE RELEASE

Buc, France, March 2007, 21st – **3D Plus announce strategic partnership with BAE Systems to deliver next generation 3D electronics packaging for avionics, automotive, medical or consumer electronics.**

BAE Systems has entered into a strategic partnership with 3D Plus, the leading company for 3D electronics packaging in Europe, to deliver bespoke 3D System-In-Package solutions enabling the achievement of new levels of performance, flexibility and development time for its electronics solutions.

Announcing the partnership with 3D Plus, James Baker, Director and General Manager of BAE Systems Advanced Technology Centre stated,

"With the increasing demand for improved electronics performance across industries and markets, we are delighted to announce our partnership with one of Europe's leading innovators in electronics technologies to deliver the next generation of packaging solutions. The partnership will enable us to bring together a unique set of research, design, development and manufacturing skills to address these performance demands."

For 3D Plus, President, Dr. Christian Val embraced the partnership approach with BAE Systems, "We are proud to partner with a global leader such as BAE Systems in order to promote our outstanding technology for new applications such as avionics, automotive, medical or consumer electronics".

The growing demand across industries to deliver higher levels of integration, lower costs and reduced time to market is driving the growth in System-In-Package solutions. With a proven pedigree in advanced 2D, 2½D and 3D electronic packaging solutions, the partnership offers a unique set of design skills, methodologies and knowledge to deliver the next generation in 3D packaged solutions.

The new design and manufacturing service recognises the different balance of drivers across markets for the adoption of high density packaging - such as size, speed, robustness, time to market and cost. Delivering reductions in size, weight and cost of 75%, 80% and 30% respectively, CirCube(tm), the integrated design and development capability, offers a range of services that can be tailored to meet a customer's specific requirements.

About 3D PLUS company :

Founded in 1996 as a spin-off of Thales, 3D Plus has become a worldwide actor for the advanced high density 3D package and die stacking technology meeting the demand for high reliability, extreme performance and very small size electronics.

Its portfolio of patented and very advanced stacking technologies starts with Package scale upward to chip-size and wafer-level packaging techniques and provides leading edge, highly integrated



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and rugged modules embedding Active, Passive, Opto-electronics and MEMS/MOEMS components.

With a broad range of catalogue products including memory modules, camera heads, power converters and computer modules, with its very miniaturized System-In-Package solutions and by Licensing its technologies, 3D PLUS meets the requirements of high technology industries in industrial, telecom., computer/blade server, military, avionics, medical and space markets.

About BAE Systems :

BAE Systems is a global defence and aerospace company delivering a full range of products and services for air, land and naval forces, as well as advanced electronics, information technology solutions and customer support services. With 88,000 employees worldwide, BAE Systems' sales exceeded £13.7 billion pounds sterling (US25.4 billion dollars) in 2006.

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